

SOT1097-2

plastic low profile ball grid array package; 228 balls, 1 mm pitch, 17 mm x 17 mm x 1.01 mm body

19 August 2021

Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	LBGA228
Package type industry code	LBGA228
Package style descriptive code	LBGA (low profile ball grid array)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	01-12-2009
Manufacturer package code	SOT1097

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	16.8	17	17.2	mm
package width	16.8	17	17.2	mm
seated height	1.15	1.36	1.5	mm
package height	0.85	1.01	1.1	mm
nominal pitch	-	1	-	mm
actual quantity of termination	-	228	-	



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2 Package outline

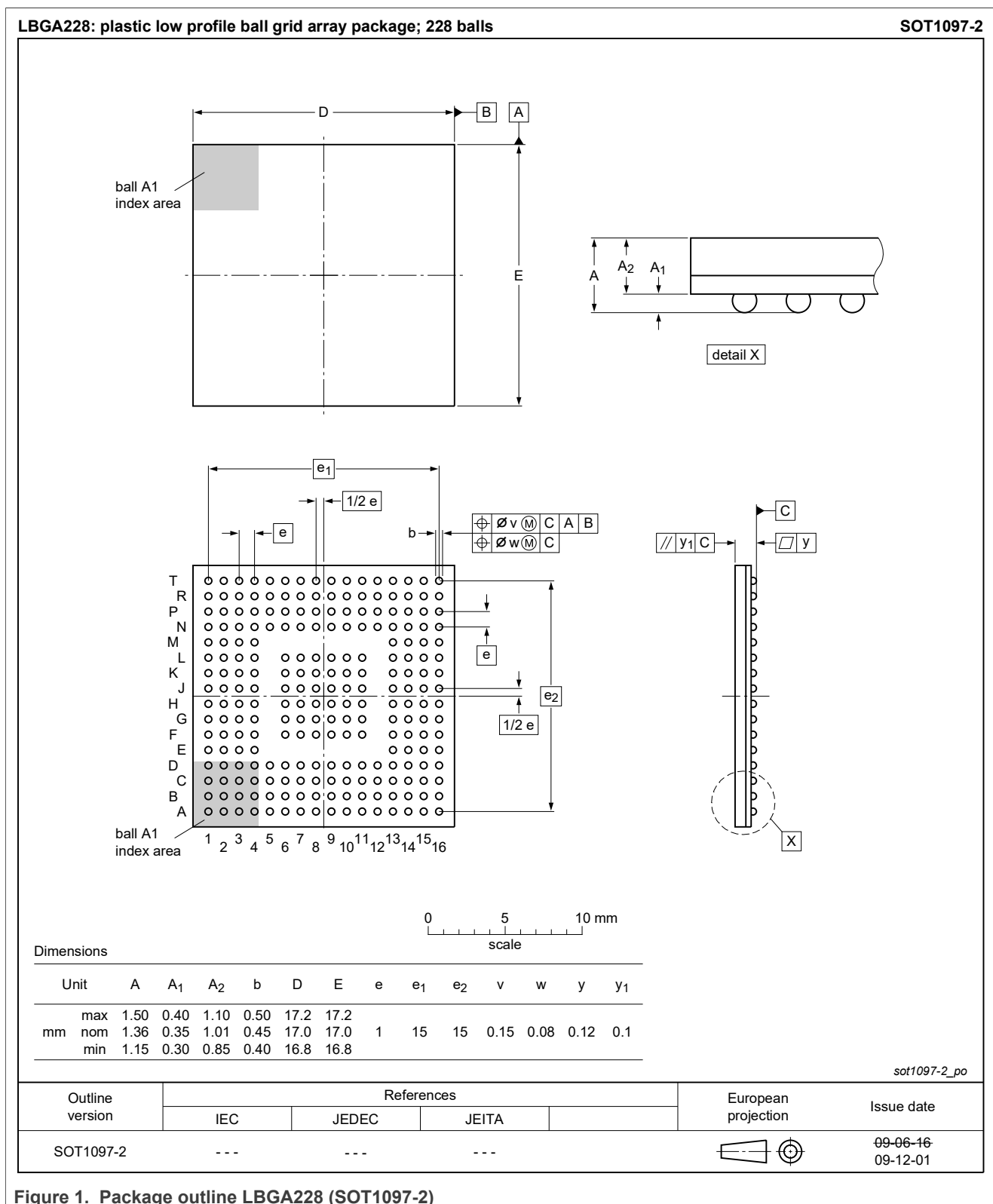


Figure 1. Package outline LBG A228 (SOT1097-2)

3 Legal information

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